



Materials Declaration

Package	LFCSP
Body Size	4 X 4
LeadCount	24
Option	Pb Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Epoxy Resin	10	1.38 E-03	40556
SiO2 Filler	85	1.17 E-02	344722
Phenol Resin	5	6.89 E-04	20278

Molding Compound		
Item	PPM	Method
Pb	4	EPA3050B (ICPAES)
Cd	<2	BSEN 1122:2001B (ICP AES)
Hg	<2	Mercury Analyser
Cr+6	<2	EPA3060A (UV)

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.63 E-02	480778
Fe	2.35	3.94 E-04	11588
P	0.03	5.03 E-06	148
Zn	0.12	2.01 E-05	592

Die Attach Paste		
Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	Not Detected	ICP AES

Internal Leadframe Plating			
	% of Plating	Weight (g)	PPM
Ag	100	2.89 E-04	8513

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	1.66 E-04	4879

Bond Wires			
	% of Wire	Weight (g)	PPM
Au	99.99	5.01 E-04	14728

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	2.12 E-03	62485

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	25	9.12 E-05	2684
Ag Filler	75	2.74 E-04	8051

Package Totals	
Weight (g)	PPM
3.40 E-02	1000000

AMK-CP-C

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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Package	LFCSP
Body Size	4 X 4
LeadCount	24
Option	Sn/Pb

Molding Compound				
Item	% of Compound	Weight (g)	PPM	
Epoxy Resin	10	1.38 E-03	40556	
SiO2 Filler	85	1.17 E-02	344722	
Phenol Resin	5	6.89 E-04	20278	

Leadframe				
Item	% of Leadframe	Weight (g)	PPM	
Cu	97.5	1.63 E-02	480778	
Fe	2.35	3.94 E-04	11588	
P	0.03	5.03 E-06	148	
Zn	0.12	2.01 E-05	592	

Internal Leadframe Plating				
	% of Plating	Weight (g)	PPM	
Ag	100	2.89 E-04	8513	

External Leadframe Plating				
Item	% of Plating	Weight (g)	PPM	
Sn	85	1.41 E-04	4147	
Pb	15	2.49 E-05	732	

Bond Wires				
	% of Wire	Weight (g)	PPM	
Au	99.99	5.01 E-04	14728	

Chip				
	% of Chip	Weight (g)	PPM	
Si	100	2.12 E-03	62485	

Die Attach				
Item	% of Die Attach	Weight (g)	PPM	
Resin	25	9.12 E-05	2684	
Ag Filler	75	2.74 E-04	8051	

Molding Compound		
Item	PPM	Method
Pb	4	EPA3050B (ICPAES)
Cd	<2	BSEN 1122:2001B (ICP AES)
Hg	<2	Mercury Analyser
Cr+6	<2	EPA3060A (UV)

Die Attach Paste		
Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	Not Detected	ICP AES

Package Totals		
Weight (g)	PPM	
3.40 E-02	1000000	

AMK-CP-A

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